

MOSFET

OptiMOS™ 5 Linear FET 2, 100 V

Features

- Ideal for hot-swap and e-fuse applications
- Very low on-resistance $R_{DS(on)}$
- Wide safe operating area SOA
- N-channel, normal level
- 100% avalanche tested
- Pb-free lead plating; RoHS compliant
- Halogen-free according to IEC61249-2-21

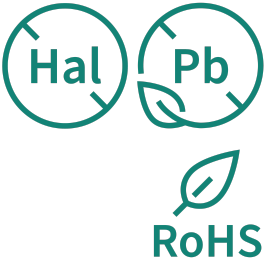
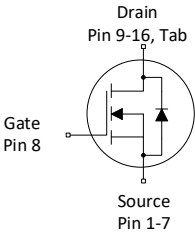
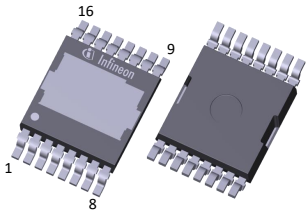
Product validation

Fully qualified according to JEDEC for Industrial Applications

Table 1 Key performance parameters

Parameter	Value	Unit
V_{DS}	100	V
$R_{DS(on),max}$	1.7	mΩ
I_D	321	A
I_{pulse} ($V_{DS}=56$ V, $t_p=10$ ms)	6.7	A

TOLT



Part number	Package	Marking	Related links
IPTC017N10NM5LF2	PG-HDSOP-16	17N10LF2	-



Table of contents

Description 1

Maximum ratings 3

Thermal characteristics 3

Electrical characteristics 4

Electrical characteristics diagrams 6

Package outlines 11

Revision history 14

Trademarks 14

Disclaimer 14

1 Maximum ratings

at $T_A=25\text{ °C}$, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Continuous drain current ¹⁾	I_D	-	-	321 227 241 32	A	$V_{GS}=10\text{ V}$, $T_C=25\text{ °C}$ $V_{GS}=10\text{ V}$, $T_C=100\text{ °C}$ $V_{GS}=15\text{ V}$, $T_C=100\text{ °C}$ $V_{GS}=10\text{ V}$, $T_A=25\text{ °C}$, $R_{thJA}=40\text{ °C/W}$ ²⁾
Pulsed drain current ³⁾	$I_{D,pulse}$	-	-	1284	A	$T_A=25\text{ °C}$
Avalanche energy, single pulse ⁴⁾	E_{AS}	-	-	775	mJ	$I_D=150\text{ A}$, $R_{GS}=25\text{ }\Omega$
Gate source voltage	V_{GS}	-20	-	20	V	-
Power dissipation	P_{tot}	-	-	375 3.8	W	$T_C=25\text{ °C}$ $T_A=25\text{ °C}$, $R_{thJA}=40\text{ °C/W}$ ²⁾
Operating and storage temperature	T_j , T_{stg}	-55	-	175	°C	-

¹⁾ Rating refers to the product only with datasheet specified absolute maximum values, maintaining case temperature as specified. For other case temperatures please refer to Diagram 2. De-rating will be required based on the actual environmental conditions.

²⁾ Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

³⁾ See Diagrams 3 and 4 for more detailed information

⁴⁾ See Diagram 14 for more detailed information

2 Thermal characteristics

Table 3 Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	0.4	°C/W	-
Thermal resistance, junction - ambient, 6 cm ² cooling area ⁵⁾	R_{thJA}	-	-	40	°C/W	
Thermal resistance, junction - ambient, minimal footprint	R_{thJA}	-	-	62	°C/W	

⁵⁾ Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

3 Electrical characteristics

at $T_j=25\text{ °C}$, unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	100	-	-	V	$V_{GS}=0\text{ V}$, $I_D=1\text{ mA}$
Gate threshold voltage	$V_{GS(th)}$	2.3	3.1	3.9	V	$V_{DS}=V_{GS}$, $I_D=280\text{ }\mu\text{A}$
Zero gate voltage drain current	I_{DSS}	-	0.1 10	1 100	μA	$V_{DS}=100\text{ V}$, $V_{GS}=0\text{ V}$, $T_j=25\text{ °C}$ $V_{DS}=100\text{ V}$, $V_{GS}=0\text{ V}$, $T_j=125\text{ °C}$
Gate-source leakage current	I_{GSS}	-	10	100	nA	$V_{GS}=20\text{ V}$, $V_{DS}=0\text{ V}$
Drain-source on-state resistance	$R_{DS(on)}$	-	1.3 1.5	1.5 1.7	m Ω	$V_{GS}=15\text{ V}$, $I_D=150\text{ A}$ $V_{GS}=10\text{ V}$, $I_D=150\text{ A}$
Gate resistance	R_G	-	1.4	2.1	Ω	-
Transconductance	g_{fs}	80	160	-	S	$ V_{DS} \geq 2 I_D R_{DS(on)max}$, $I_D=150\text{ A}$

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Input capacitance ⁶⁾	C_{iss}	-	13000	17000	pF	$V_{GS}=0\text{ V}$, $V_{DS}=50\text{ V}$, $f=1\text{ MHz}$
Output capacitance ⁶⁾	C_{oss}	-	1800	2300	pF	
Reverse transfer capacitance ⁶⁾	C_{rss}	-	35	61	pF	
Turn-on delay time	$t_{d(on)}$	-	29	-	ns	$V_{DD}=50\text{ V}$, $V_{GS}=10\text{ V}$, $I_D=100\text{ A}$, $R_{G,ext}=1.6\text{ }\Omega$
Rise time	t_r	-	24	-	ns	
Turn-off delay time	$t_{d(off)}$	-	45	-	ns	
Fall time	t_f	-	20	-	ns	

⁶⁾ Defined by design. Not subject to production test.

Table 6 Gate charge characteristics ⁷⁾

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	84	-	nC	$V_{DD}=50\text{ V}$, $I_D=100\text{ A}$, $V_{GS}=0\text{ to }10\text{ V}$
Gate charge at threshold	$Q_{g(th)}$	-	41	-	nC	
Gate to drain charge ⁸⁾	Q_{gd}	-	27	41	nC	
Switching charge	Q_{sw}	-	70	-	nC	
Gate charge total ⁸⁾	Q_g	-	165	206	nC	
Gate plateau voltage	$V_{plateau}$	-	6.4	-	V	$V_{DS}=0.1\text{ V}$, $V_{GS}=0\text{ to }10\text{ V}$
Gate charge total, sync. FET	$Q_{g(sync)}$	-	150	-	nC	
Output charge ⁸⁾	Q_{oss}	-	211	281	nC	

⁷⁾ See "Gate charge waveforms" for parameter definition

⁸⁾ Defined by design. Not subject to production test.

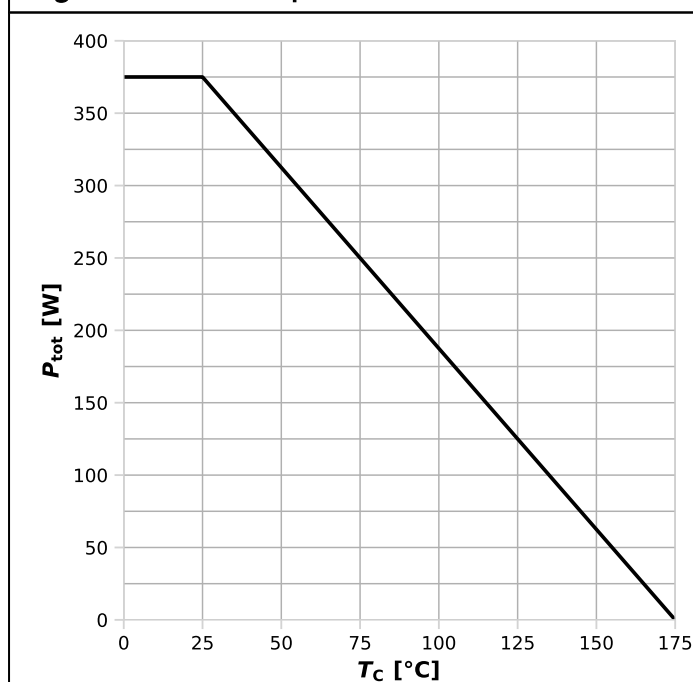
Table 7 Reverse diode

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Diode continuous forward current	I_S	-	-	252	A	$T_C=25\text{ °C}$
Diode pulse current	$I_{S,pulse}$	-	-	1284	A	
Diode forward voltage	V_{SD}	-	0.85	1.2	V	$V_{GS}=0\text{ V}$, $I_F=100\text{ A}$, $T_J=25\text{ °C}$
Reverse recovery time ⁹⁾	t_{rr}	-	58	116	ns	$V_R=50\text{ V}$, $I_F=100\text{ A}$, $di_F/dt=100\text{ A}/\mu\text{s}$
Reverse recovery charge ⁹⁾	Q_{rr}	-	103	206	nC	

⁹⁾ Defined by design. Not subject to production test.

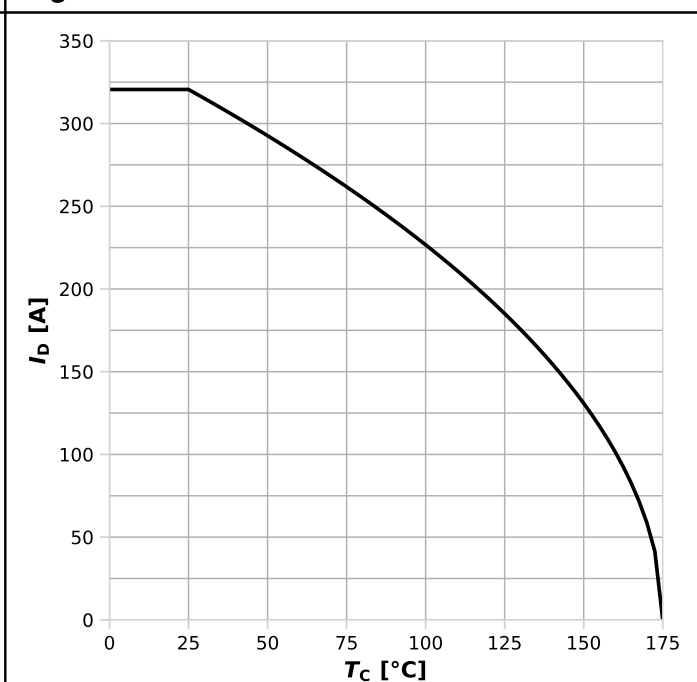
4 Electrical characteristics diagrams

Diagram 1: Power dissipation



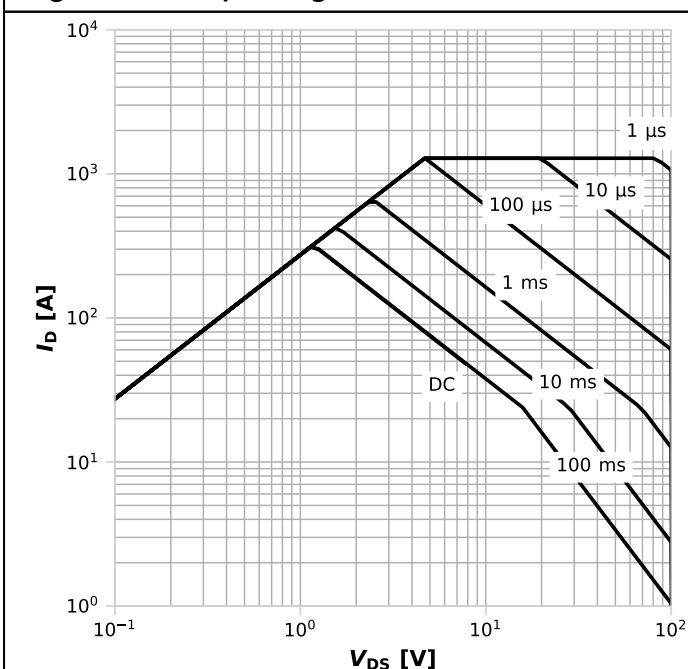
$$P_{tot}=f(T_c)$$

Diagram 2: Drain current



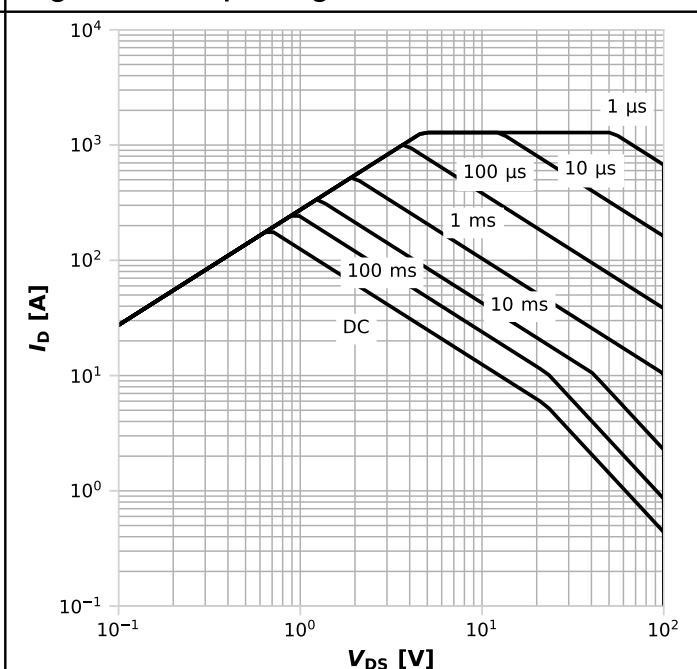
$$I_D=f(T_c); V_{GS} \geq 10 \text{ V}$$

Diagram 3: Safe operating area



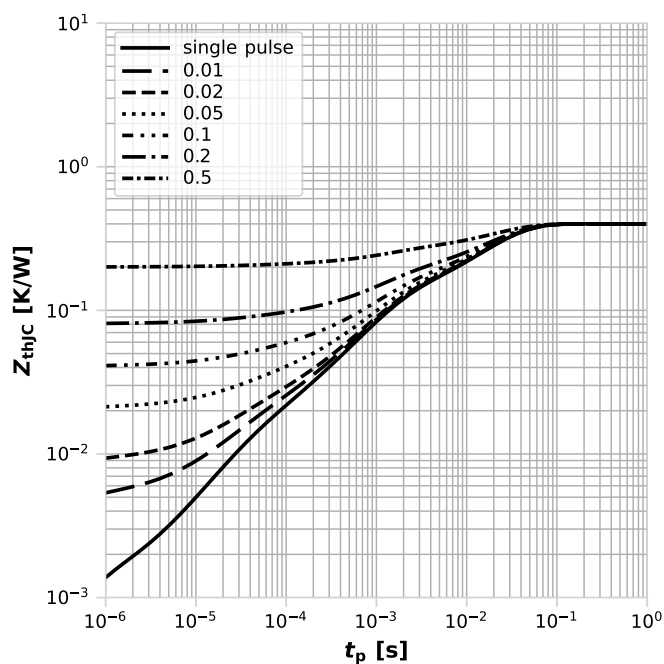
$$I_D=f(V_{DS}); T_c=25 \text{ °C}; D=0; \text{parameter: } t_p$$

Diagram 4: Safe operating area



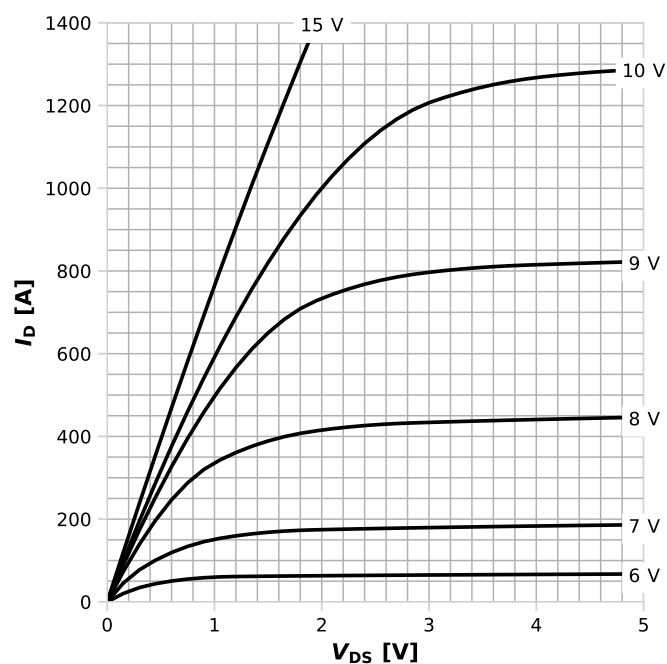
$$I_D=f(V_{DS}); T_c=125 \text{ °C}; D=0; \text{parameter: } t_p$$

Diagram 5: Max. transient thermal impedance



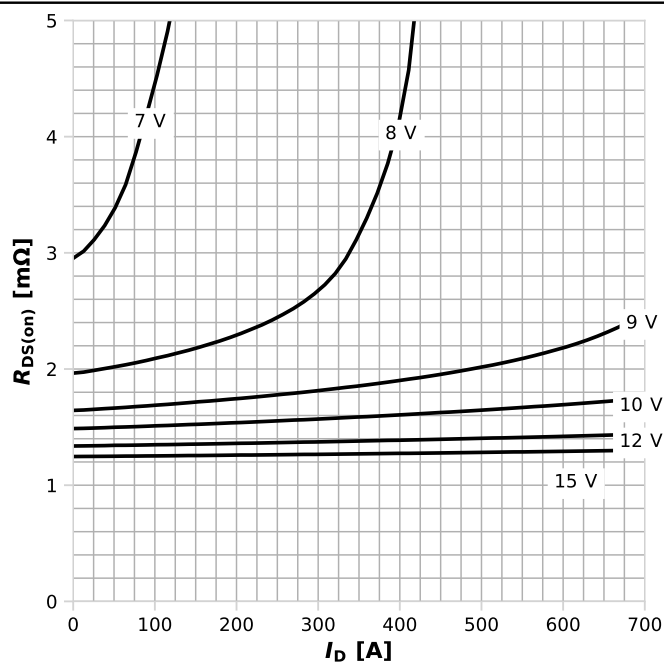
$$Z_{thJC} = f(t_p); \text{ parameter: } D = t_p / T$$

Diagram 6: Typ. output characteristics



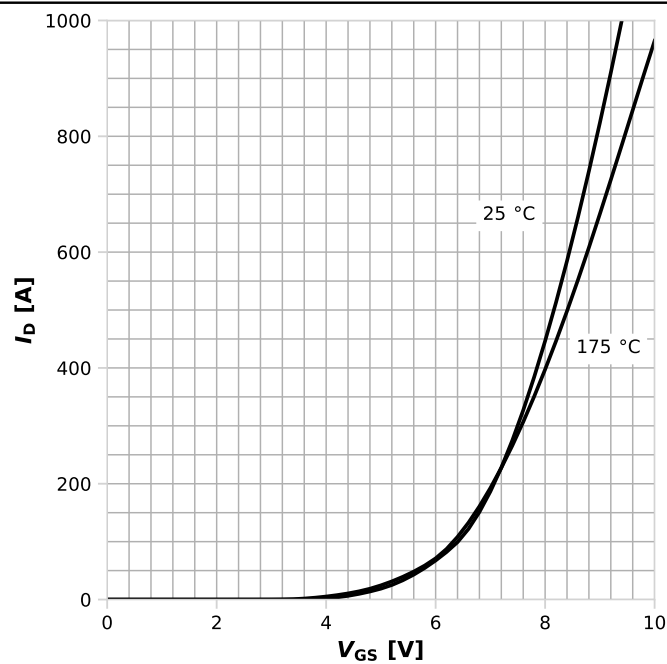
$$I_D = f(V_{DS}, T_j = 25^\circ\text{C}; \text{ parameter: } V_{GS})$$

Diagram 7: Typ. drain-source on resistance



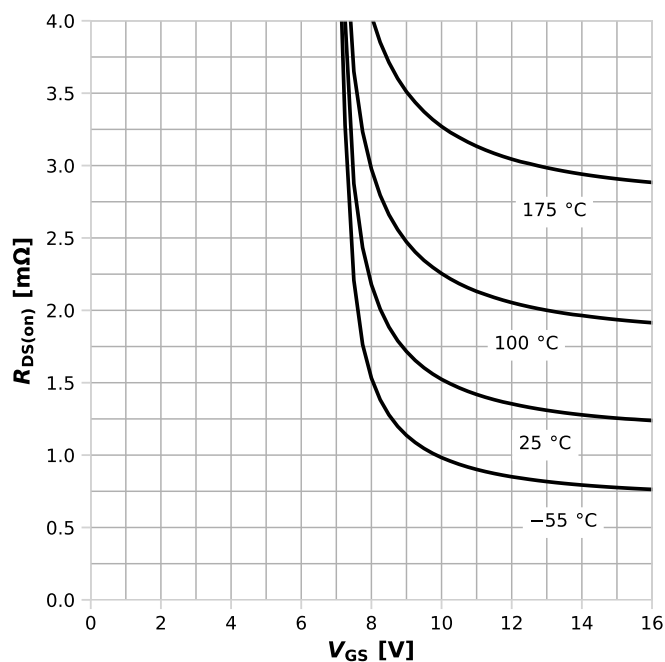
$$R_{DS(on)} = f(I_D, T_j = 25^\circ\text{C}; \text{ parameter: } V_{GS})$$

Diagram 8: Typ. transfer characteristics



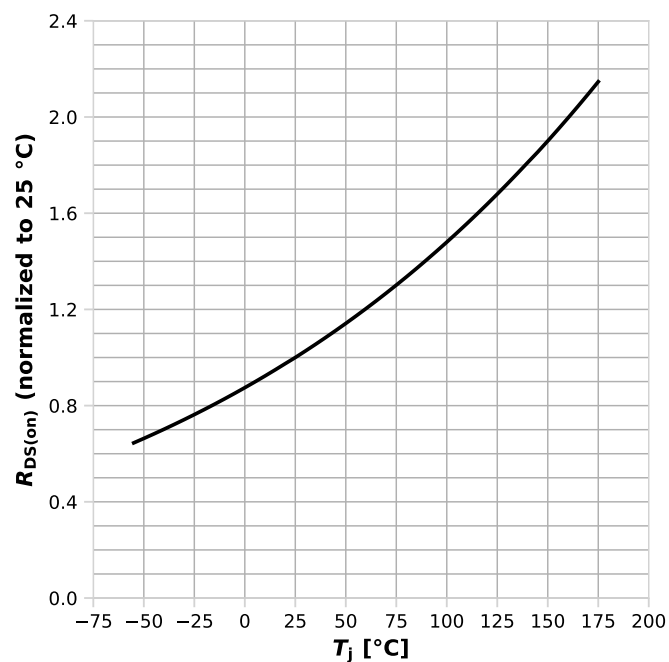
$$I_D = f(V_{GS}, |V_{DS}| > 2|I_D|R_{DS(on)max}; \text{ parameter: } T_j)$$

Diagram 9: Typ. drain-source on resistance



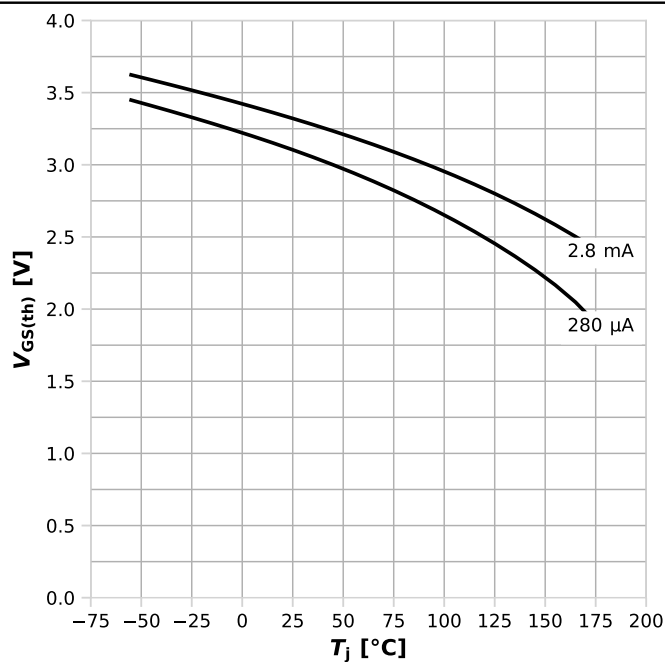
$$R_{DS(on)} = f(V_{GS}), I_D = 150 \text{ A; parameter: } T_j$$

Diagram 10: Normalized drain-source on resistance



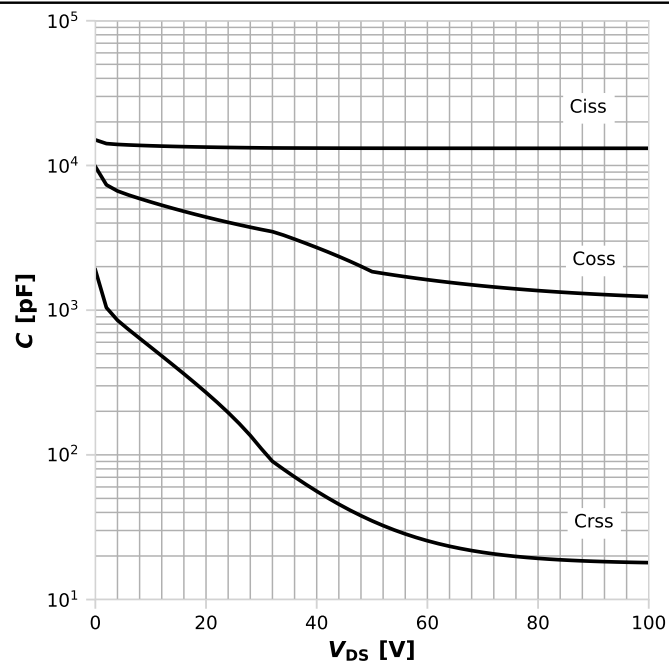
$$R_{DS(on)} = f(T_j), I_D = 150 \text{ A, } V_{GS} = 10 \text{ V}$$

Diagram 11: Typ. gate threshold voltage



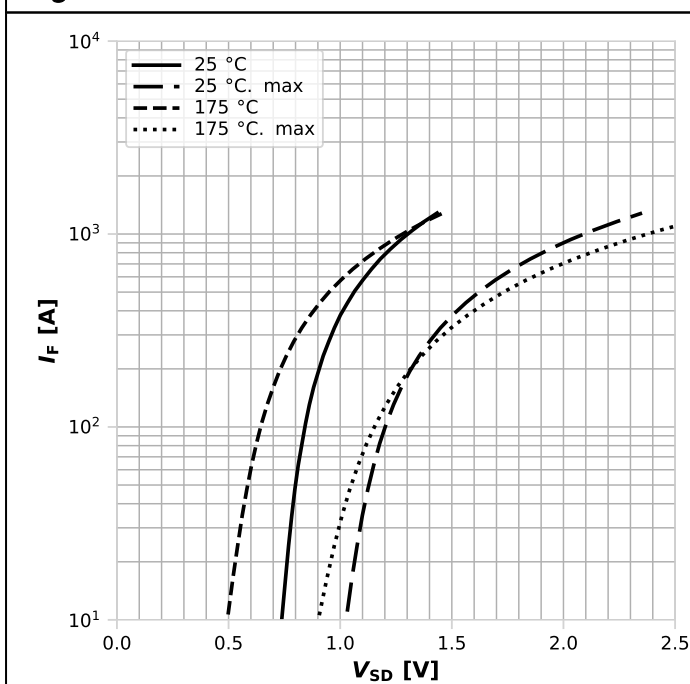
$$V_{GS(th)} = f(T_j), V_{GS} = V_{DS}; \text{ parameter: } I_D$$

Diagram 12: Typ. capacitances



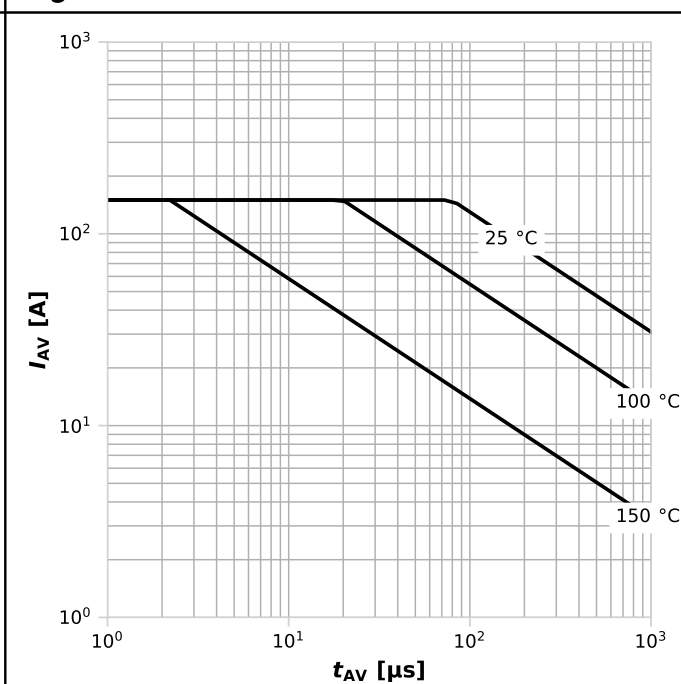
$$C = f(V_{DS}); V_{GS} = 0 \text{ V; } f = 1 \text{ MHz}$$

Diagram 13: Forward characteristics of reverse diode



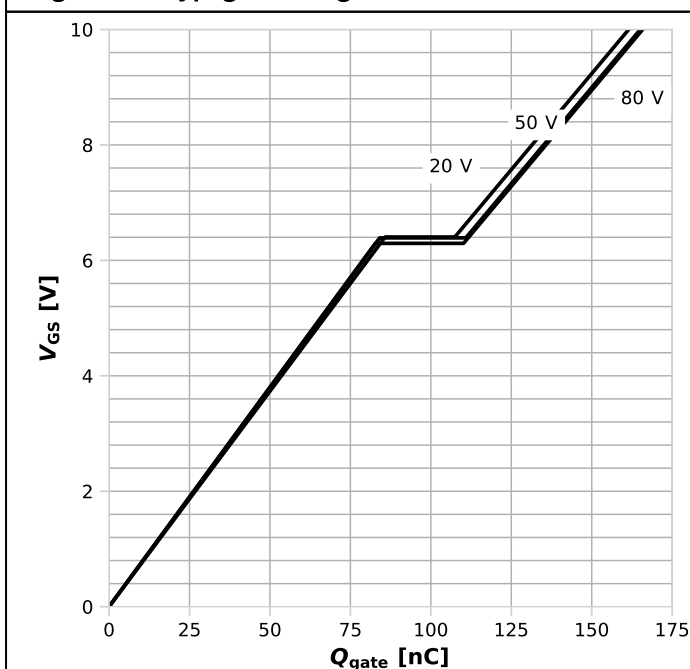
$I_F = f(V_{SD})$; parameter: T_j

Diagram 14: Avalanche characteristics



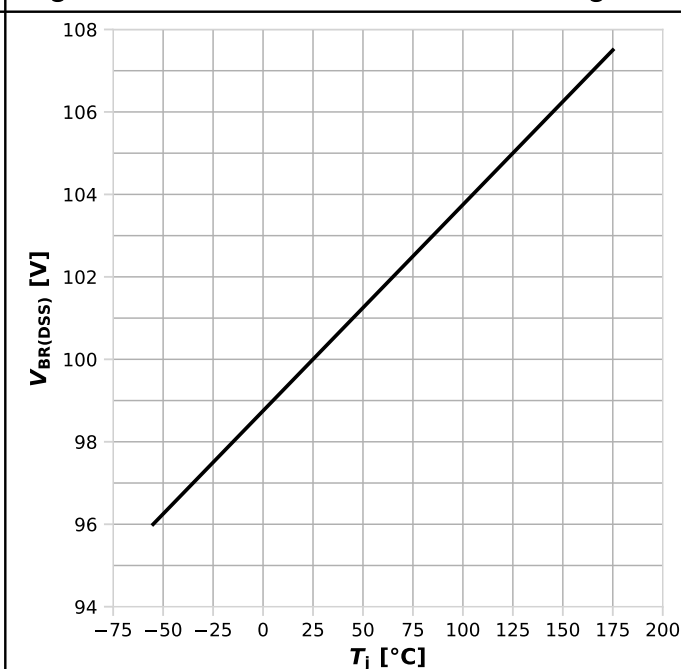
$I_{AS} = f(t_{AV})$; $R_{GS} = 25 \Omega$; parameter: $T_{j,start}$

Diagram 15: Typ. gate charge



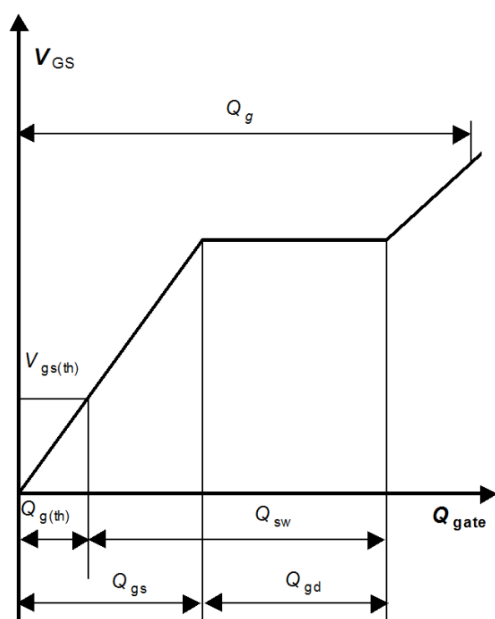
$V_{GS} = f(Q_{gate})$, $I_D = 100 \text{ A pulsed}$, $T_j = 25 \text{ °C}$; parameter: V_{DD}

Diagram 16: Min. drain-source breakdown voltage



$V_{BR(DSS)} = f(T_j)$; $I_D = 1 \text{ mA}$

Gate charge waveforms



5 Package outlines

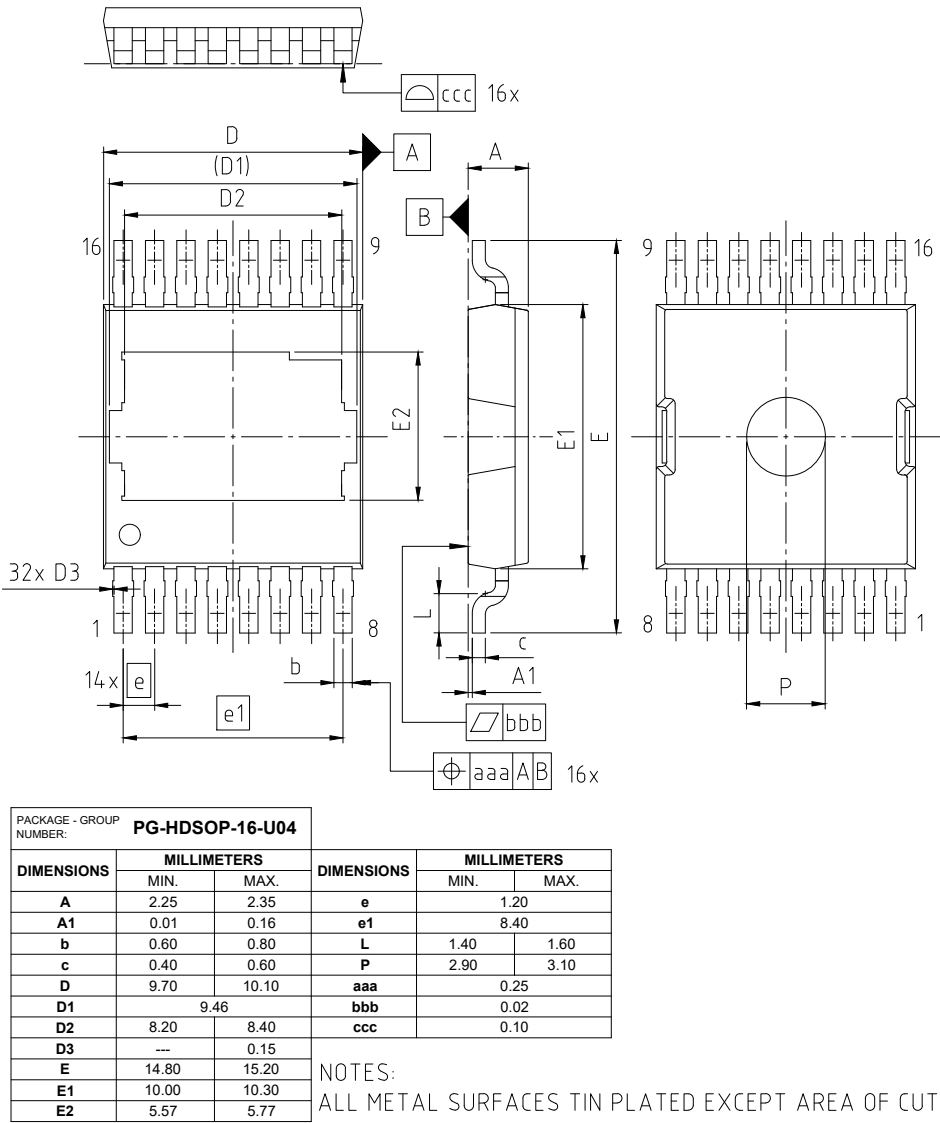


Figure 1 Outline PG-HDSOP-16, dimensions in mm

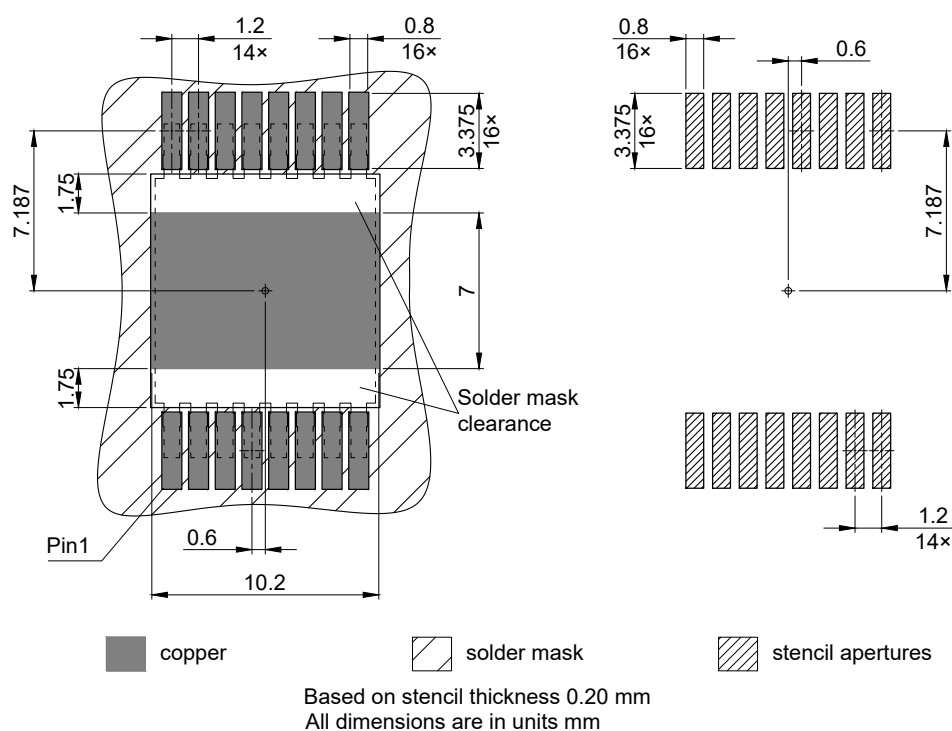
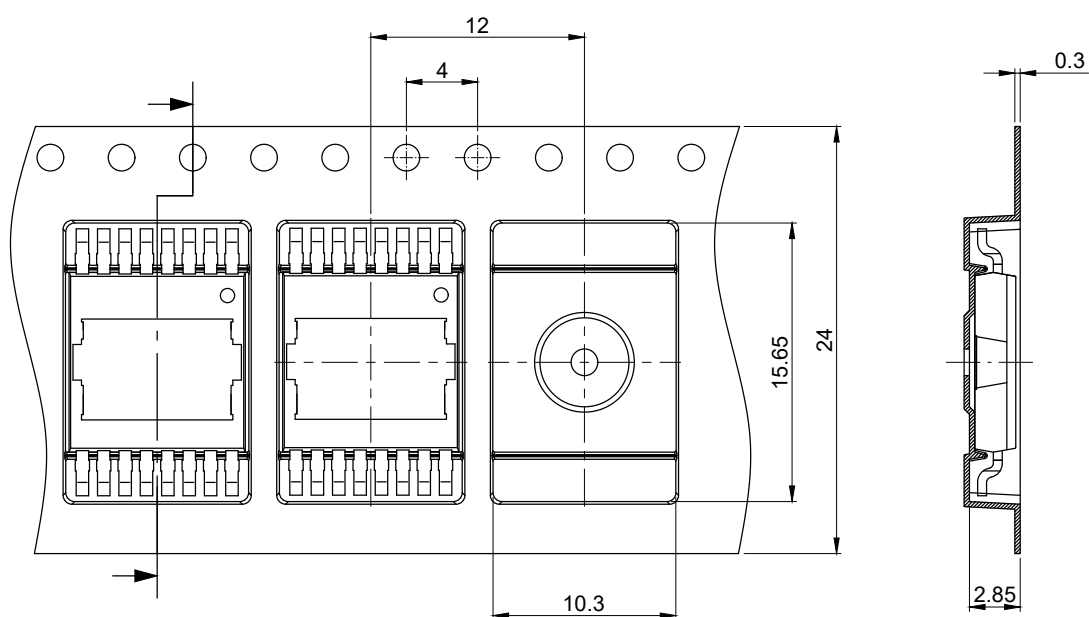


Figure 2 Footprint drawing PG-HDSOP-16, dimensions in mm



All dimensions are in units mm


The drawing is in compliance with ISO 128-30, Projection Method 1 []

Figure 3 Packaging variant PG-HDSOP-16, dimensions in mm

Revision history

IPTC017N10NM5LF2

Revision 2025-01-24, Rev. 1.0

Previous revisions

Revision	Date	Subjects (major changes since last revision)
1.0	2025-01-24	Release of final datasheet

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